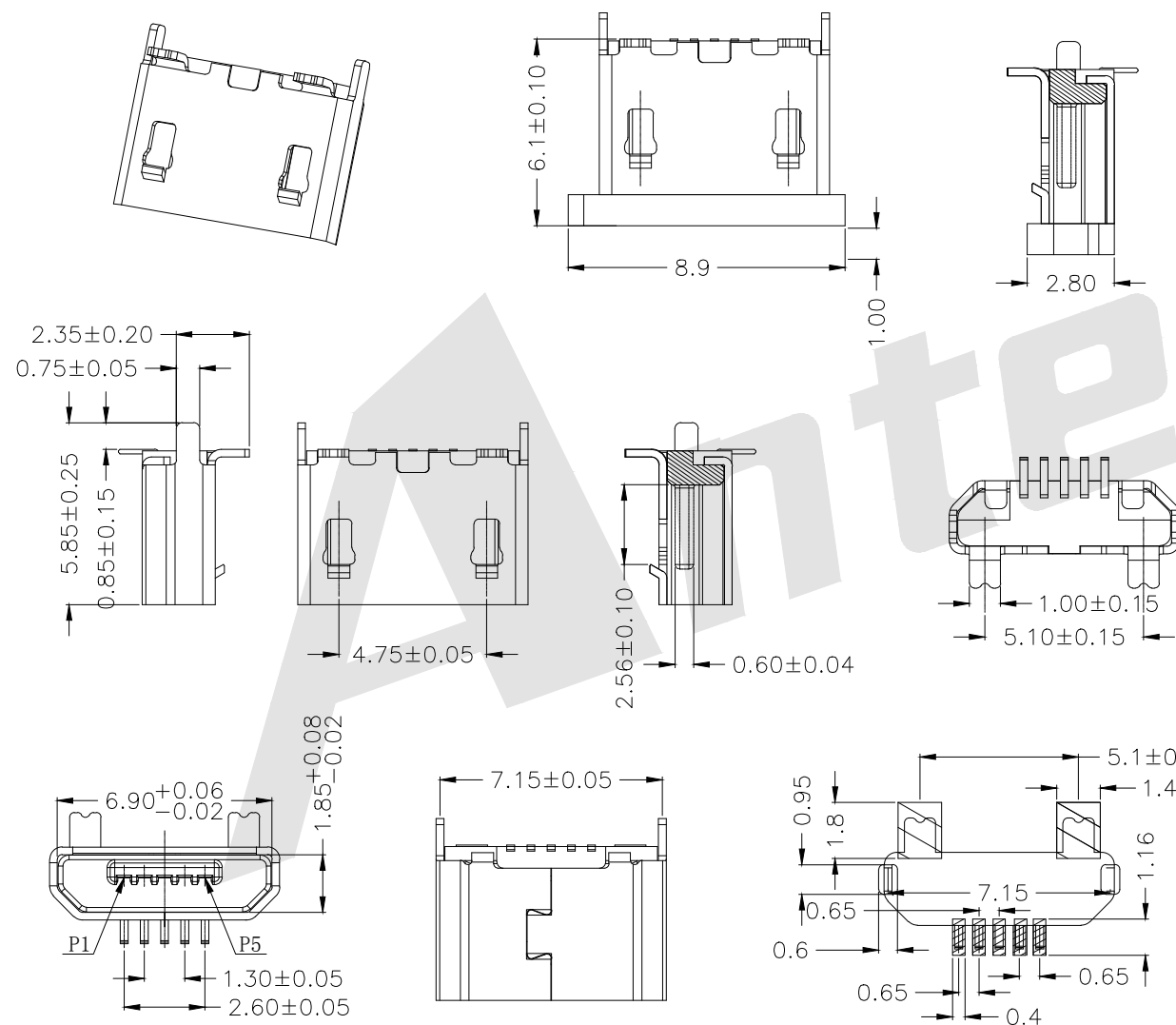


HSF



ROHS



PCB LAYOUT

SPECIFICATIONS:

- 1.1 Current Rating:1A Max
- 1.2 Voltage Rating:30V DC
- 1.3 Withstanding Voltage:500V(ac) For 1min
- 1.4 Contact Resistance:50mΩ Max
- 1.5 Insulation Resistance:1000MΩ Min
- 1.6 Total Mating Force:3.57kgf Max

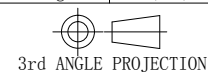
Order Code:

MUFM52 - X - X - X - X - X - X
① ② ③ ④ ⑤ ⑥ ⑦

- ① Series NO:
- ② Shell Material:
B:Brass I:Iron
S:stainless steel
- ③ Insulator Material:
P:PBT+30%GF
L:LCP
- ④ Contact Material:
B:Brass
P:Phosphor Copper
- ⑤ Shell Material:
A:Copper Alloy
B:C2680/Stainless
C:Steel 201
- ⑥ Contact Plating
G0:Gold flash
G1: 3U" Gold
G2: 5U" Gold
G3:10U" Gold
G4:15U" Gold
G5:30U" Gold
- ⑦ Packing
A:Tray
B:Bag
C:Tape
D:Tape & Reel+Cap

Unless Otherwise specified tolerance

X. ±0.35 X.XX: ±0.20
X.X: ±0.25 X.XXX: ±0.15

SCALE:
As ShownUNIT:
mmDRAW
Wu Feng RongDATE
11/25/2020CHECK
BobYangDATE
11/25/2020

3rd ANGLE PROJECTION



ANTENK ELECTRONICS CO.,LTD
Http://www.antenk.com
E-mail:sales@antenk.com

TITLE: Micro USB 5P B Type
Female Vertical SMT

DRAWING NO: MUFM52-XXXXXX

PRODUCT NO: MUFM52-XXXXXX



ADD "A, B, C" TYPE

04/19/2021

DESCRIPTION

DATE

REV

1

2

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4

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